Wangs, Switzerland
Production site for substrates and hybrid circuits

The Cicor site in Wangs (Reinhardt Microtech AG) specializes in the production of rigid and flexible substrates in thin-film technology and has extensive manufacturing expertise in this field. The production takes place in the clean room using microelectronic manufacturing processes such as lithography, sputtering, evaporation, etching, electroplating and passive balancing of resistances. Further machining operations are laser drilling of holes, minimum 60 µm, laser cutting of contours and sawing as separation step from multiple use to chip. The production and processes are designed for maximum flexibility in order to meet special requirements for substrate materials and process combinations. The site produces thin-film substrates on Al₂O₃, AlN, LCP, polyimide, glass and quartz in prototype and series production.
Competencies and services

**Thin-film substrates**
- Rigid and flexible substrates, multilayers
- Flexible multilayer circuits with very high resolution (10 µm)
- Metallic coating
- Sputtering
- Electroplating (copper, nickel, gold)
- Photolithography
- Wet etching, dry etching (RIE)
- Eutectic AuSn by evaporation
- Clean rooms ISO class 7 und ISO class 5 (class 10,000 bis 100), 660 m²

**Automatic laser trimming**
- Laser trimming using a YAG laser
- High-value resistors

**Forming and singulating**
- CO₂ laser cutting
- Diamond cutting

Markets

- Industrial
- Medical
- Aerospace and defence
- Communication

Certifications

- ISO 9001 Quality
- EN 9100 Aerospace

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The Cicor Group is a globally active provider of full-cycle electronic solutions from research and development to manufacturing and supply chain management. Cicor’s approximately 2300 employees at twelve locations in Europe and Asia are serving leaders from the medical, industrial and aerospace & defence industries. Cicor creates value to its customers through the combination of customer-specific development solutions, high-tech components, as well as electronic device manufacturing.